

SPC6801

DESCRIPTION

The SPC6801 combines the Trench MOSFET technology with a very low forward voltage drop Schottky barrier rectifier in an TSOP-6P package. The Trench MOSFET is the P-Channel enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology. This high density process is especially tailored to minimize on-state resistance and provide superior switching performance. The Schottky diode is provided to facilitate the implementation of a bidirectional blocking switch, or for DC-DC conversion applications.

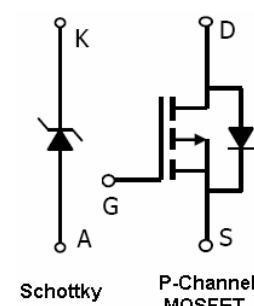
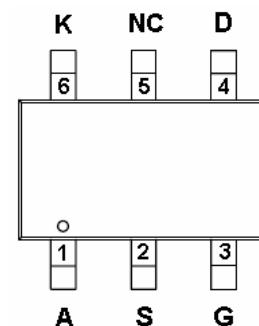
FEATURES

- ◆ P-Channel
 - 30V/-2.8A,RDS(ON)=105mΩ@VGS=- 10V
 - 30V/-2.5A,RDS(ON)=115mΩ@VGS=-4.5V
 - 30V/-1.5A,RDS(ON)=150mΩ@VGS=-2.5V
- ◆ Schottky
 - VKA (V) = 20V, IF = 1A, VF<0.5V@0.5A
- ◆ Super high density cell design for extremely low RDS (ON)
- ◆ Exceptional on-resistance and maximum DC current capability
- ◆ TSOP- 6P package design

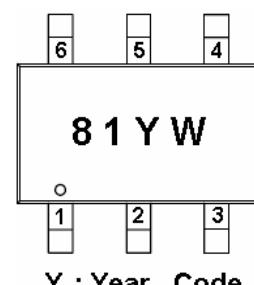
APPLICATIONS

- Battery Powered System
- DC/DC Converter
- Load Switch
- Cell Phone

PIN CONFIGURATION(TSOP- 6P)



PART MARKING





SPC6801

PIN DESCRIPTION

Pin	Symbol	Description
1	A	Schottky Anode
2	S	MOSFET Source
3	G	MOSFET Gate
4	D	MOSFET Drain
5	NC	No Connect
6	K	Schottky Cathode

ORDERING INFORMATION

Part Number	Package	Part Marking
SPC6801ST6RG	TSOP- 6P	81YW

※ Week Code : A ~ Z(1 ~ 26) ; a ~ z(27 ~ 52)

※ SPC6801ST6RG : Tape Reel ; Pb – Free

ABSOLUTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical		Unit
		P-Channel	Schottky	
Drain-Source Voltage	V _{DSS}	-30		V
Gate –Source Voltage	V _{GSS}	±12		V
Continuous Drain Current(T _J =150°C)	T _A =25°C	ID	-2.8	A
	T _A =70°C		-2.1	
Pulsed Drain Current	I _{DM}	-10		A
Schottky Reverse Voltage	V _{KA}		20	V
Continuous Forward Current	T _A =25°C	I _F	1	A
	T _A =70°C		0.7	
Pulsed Forward Current	I _{FM}		10	A
Continuous Source Current(Diode Conduction)	I _S	-1.4		A
Power Dissipation	T _A =25°C	P _D	1.15	W
	T _A =70°C		0.75	
Operating Junction Temperature	T _J	-55/150		°C
Storage Temperature Range	T _{STG}	-55/150		°C
Thermal Resistance-Junction to Ambient	T ≤ 10sec	R _{θJA}	52	°C/W
	Steady State		90	



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ELECTRICAL CHARACTERISTICS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
MOSFET Static						
Drain-Source Breakdown Voltage	V(BR)DSS	VGS=0V, ID=-10uA	-30			V
Gate Threshold Voltage	VGS(th)	VDS=VGS, ID=-250uA	-0.4		-1.0	
Gate Leakage Current	IGSS	VDS=0V, VGS=±20V			±100	nA
Zero Gate Voltage Drain Current	IDSS	VDS=-24V, VGS=0V			-1	uA
		VDS=-24V, VGS=0V TJ=55°C			-10	
On-State Drain Current	ID(on)	VDS= -5V, VGS =-4.5V	-4			A
Drain-Source On-Resistance	RDS(on)	VGS=-10V, ID=-2.8A		0.085	0.105	Ω
		VGS=-4.5V, ID=-2.5A		0.100	0.115	
		VGS=-2.5V, ID=-1.5A		0.135	0.150	
Forward Transconductance	gfs	VDS=-10V, ID=-2.8A		4.0		S
Diode Forward Voltage	VSD	IS=-1.2A, VGS=0V		-0.8	-1.2	V
MOSFET Dynamic						
Total Gate Charge	Qg	VDS=-15V , VGS=-4.5V ID=-2.0A		5.8		nC
Gate-Source Charge	Qgs			0.8		
Gate-Drain Charge	Qgd			1.5		
Input Capacitance	Ciss	VDS=-15V , VGS=0V f=1MHz		380		pF
Output Capacitance	Coss			55		
Reverse Transfer Capacitance	Crss			40		
Turn-On Time	td(on)	VDD=-15V , RL=15Ω ID=-1.0A , VGEN=-10V RG=3Ω		6		ns
	tr			3.9		
Turn-Off Time	td(off)			40		
	tr			15		
Schottky Parameters						
Forward Voltage Drop	VF	IF = 500mA		0.41	0.47	V
Reverse Breakdown Voltage	VBR	IR = 500uA	20			V
Maximum reverse leakage current	Irm	VR = 20V			0.1	mA
		VR = 20V , TJ=70°C			1	
Junction Capacitance	CT	VR = 10V		31		pF
		VR = 0V , f=1MHz		120		
Schottky Reverse Recovery Time	Tr	IF=1A, dI/dt=100A/μs		5.4	10	ns
Schottky Reverse Recovery Charge	Qrr	IF=1A, dI/dt=100A/μs		0.8		nC